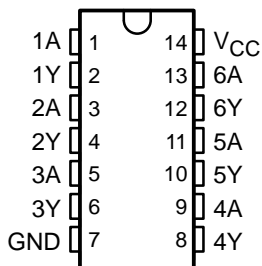


# SN54AHCT04, SN74AHCT04 HEX INVERTERS

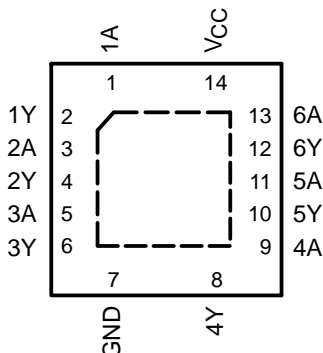
SCLS232N – OCTOBER 1995 – REVISED JULY 2003

- Inputs Are TTL-Voltage Compatible
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)

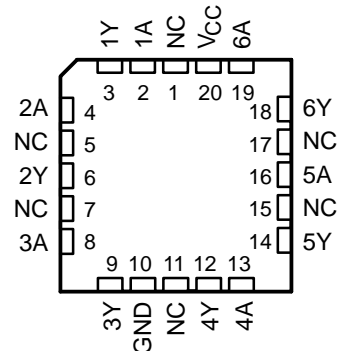
SN54AHCT04 . . . J OR W PACKAGE  
SN74AHCT04 . . . D, DB, DGV, N, NS,  
OR PW PACKAGE  
(TOP VIEW)



SN74AHCT04 . . . RGY PACKAGE  
(TOP VIEW)



SN54AHCT04 . . . FK PACKAGE  
(TOP VIEW)



NC – No internal connection

## description/ordering information

The 'AHCT04 devices contain six independent inverters. These devices perform the Boolean function  $Y = \bar{A}$ .

## ORDERING INFORMATION

| T <sub>A</sub> | PACKAGE†    |               | ORDERABLE PART NUMBER | TOP-SIDE MARKING |
|----------------|-------------|---------------|-----------------------|------------------|
| –40°C to 85°C  | QFN – RGY   | Tape and reel | SN74AHCT04RGYR        | HB04             |
|                | PDIP – N    | Tube          | SN74AHCT04N           | SN74AHCT04N      |
|                | SOIC – D    | Tube          | SN74AHCT04D           | AHCT04           |
|                |             | Tape and reel | SN74AHCT04DR          |                  |
|                | SOP – NS    | Tape and reel | SN74AHCT04NSR         | AHCT04           |
|                | SSOP – DB   | Tape and reel | SN74AHCT04DBR         | HB04             |
|                | TSSOP – PW  | Tube          | SN74AHCT04PW          | HB04             |
|                |             | Tape and reel | SN74AHCT04PWR         |                  |
| –55°C to 125°C | TVSOP – DGV | Tape and reel | SN74AHCT04DGV         | HB04             |
|                | CDIP – J    | Tube          | SNJ54AHCT04J          | SNJ54AHCT04J     |
|                | CFP – W     | Tube          | SNJ54AHCT04W          | SNJ54AHCT04W     |
|                | LCCC – FK   | Tube          | SNJ54AHCT04FK         | SNJ54AHCT04FK    |

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).

FUNCTION TABLE  
(each inverter)

| INPUT<br>A | OUTPUT<br>Y |
|------------|-------------|
| H          | L           |
| L          | H           |



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS  
INSTRUMENTS**

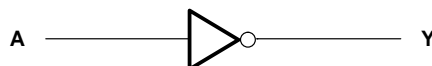
POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

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# SN54AHCT04, SN74AHCT04 HEX INVERTERS

SCLS232N – OCTOBER 1995 – REVISED JULY 2003

## logic diagram, each inverter (positive logic)



## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

|  |                            |
|--|----------------------------|
| Supply voltage range, $V_{CC}$                                   | –0.5 V to 7 V              |
| Input voltage range, $V_I$ (see Note 1)                          | –0.5 V to 7 V              |
| Output voltage range, $V_O$ (see Note 1)                         | –0.5 V to $V_{CC} + 0.5$ V |
| Input clamp current, $I_{IK}$ ( $V_I < 0$ )                      | –20 mA                     |
| Output clamp current, $I_{OK}$ ( $V_O < 0$ or $V_O > V_{CC}$ )   | ±20 mA                     |
| Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ )       | ±25 mA                     |
| Continuous current through $V_{CC}$ or GND                       | ±50 mA                     |
| Package thermal impedance, $\theta_{JA}$ (see Note 2): D package | 86°C/W                     |
| (see Note 2): DB package   | 96°C/W                     |
| (see Note 2): DGV package  | 127°C/W                    |
| (see Note 2): N package  | 80°C/W                     |
| (see Note 2): NS package   | 76°C/W                     |
| (see Note 2): PW package   | 113°C/W                    |
| (see Note 3): RGY package  | 47°C/W                     |
| Storage temperature range, $T_{stg}$                             | –65°C to 150°C             |

<sup>†</sup> Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.  
2. The package thermal impedance is calculated in accordance with JESD 51-7.  
3. The package thermal impedance is calculated in accordance with JESD 51-5.

## recommended operating conditions (see Note 4)

|  | SN54AHCT04 |          | SN74AHCT04 |          | UNIT |
|--|------------|----------|------------|----------|------|
|  | MIN        | MAX      | MIN        | MAX      |      |
| $V_{CC}$ Supply voltage                                | 4.5        | 5.5      | 4.5        | 5.5      | V    |
| $V_{IH}$ High-level input voltage                      | 2          |          | 2          |          | V    |
| $V_{IL}$ Low-level input voltage                       |            | 0.8      |            | 0.8      | V    |
| $V_I$ Input voltage                                    | 0          | 5.5      | 0          | 5.5      | V    |
| $V_O$ Output voltage                                   | 0          | $V_{CC}$ | 0          | $V_{CC}$ | V    |
| $I_{OH}$ High-level output current                     |            | –8       |            | –8       | mA   |
| $I_{OL}$ Low-level output current                      |            | 8        |            | 8        | mA   |
| $\Delta t/\Delta v$ Input transition rise or fall rate |            | 20       |            | 20       | ns/V |
| $T_A$ Operating free-air temperature                   | –55        | 125      | –40        | 85       | °C   |

NOTE 4: All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER          | TEST CONDITIONS   | V <sub>CC</sub> | T <sub>A</sub> = 25°C |     |      | SN54AHCT04 |      | SN74AHCT04 |      | UNIT |
|--------------------|---|-----------------|-----------------------|-----|------|------------|------|------------|------|------|
|                    |   |                 | MIN                   | TYP | MAX  | MIN        | MAX  | MIN        | MAX  |      |
| V <sub>OH</sub>    | I <sub>OH</sub> = -50 µA                                      | 4.5 V           | 4.4                   | 4.5 |      | 4.4        |      | 4.4        |      | V    |
|                    | I <sub>OH</sub> = -8 mA                                       |                 | 3.94                  |     |      | 3.8        |      | 3.8        |      |      |
| V <sub>OL</sub>    | I <sub>OL</sub> = 50 µA                                       | 4.5 V           |                       |     | 0.1  |            | 0.1  |            | 0.1  | V    |
|                    | I <sub>OL</sub> = 8 mA  |                 |                       |     | 0.36 |            | 0.44 |            | 0.44 |      |
| I <sub>I</sub>     | V <sub>I</sub> = 5.5 V or GND                                 | 0 V to 5.5 V    |                       |     | ±0.1 |            | ±1*  |            | ±1   | µA   |
| I <sub>CC</sub>    | V <sub>I</sub> = V <sub>CC</sub> or GND, I <sub>O</sub> = 0   | 5.5 V           |                       |     | 2    |            | 20   |            | 20   | µA   |
| ΔI <sub>CC</sub> † | One input at 3.4 V,<br>Other inputs at V <sub>CC</sub> or GND | 5.5 V           |                       |     | 1.35 |            | 1.5  |            | 1.5  | mA   |
| C <sub>i</sub>     | V <sub>I</sub> = V <sub>CC</sub> or GND                       | 5 V             |                       | 4   | 10   |            |      |            | 10   | pF   |

\* On products compliant to MIL-PRF-38535, this parameter is not production tested at V<sub>CC</sub> = 0 V.

† This is the increase in supply current for each input at one of the specified TTL voltage levels, rather than 0 V or V<sub>CC</sub>.

switching characteristics over recommended operating free-air temperature range,  
V<sub>CC</sub> = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

| PARAMETER        | FROM (INPUT) | TO (OUTPUT) | LOAD CAPACITANCE       | T <sub>A</sub> = 25°C |       |       | SN54AHCT04 |       | SN74AHCT04 |     | UNIT |
|------------------|--------------|-------------|------------------------|-----------------------|-------|-------|------------|-------|------------|-----|------|
|                  |              |             |                        | MIN                   | TYP   | MAX   | MIN        | MAX   | MIN        | MAX |      |
| t <sub>PLH</sub> | A            | Y           | C <sub>L</sub> = 15 pF |                       | 4.7** | 6.7** | 1**        | 7.5** | 1          | 7.5 | ns   |
| t <sub>PHL</sub> |              |             |                        |                       | 4.7** | 6.7** | 1**        | 7.5** | 1          | 7.5 |      |
| t <sub>PLH</sub> | A            | Y           | C <sub>L</sub> = 50 pF |                       | 5.5   | 7.7   | 1          | 8.5   | 1          | 8.5 | ns   |
| t <sub>PHL</sub> |              |             |                        |                       | 5.5   | 7.7   | 1          | 8.5   | 1          | 8.5 |      |

\*\* On products compliant to MIL-PRF-38535, this parameter is not production tested.

noise characteristics, V<sub>CC</sub> = 5 V, C<sub>L</sub> = 50 pF, T<sub>A</sub> = 25°C (see Note 5)

| PARAMETER          |   | SN74AHCT04 |      |     | UNIT |
|--------------------|---|------------|------|-----|------|
|                    |   | MIN        | TYP  | MAX |      |
| V <sub>OL(P)</sub> | Quiet output, maximum dynamic V <sub>OL</sub> |            | 0.8  |     | V    |
| V <sub>OL(V)</sub> | Quiet output, minimum dynamic V <sub>OL</sub> |            | -0.8 |     | V    |
| V <sub>OH(V)</sub> | Quiet output, minimum dynamic V <sub>OH</sub> |            | 4.7  |     | V    |
| V <sub>IH(D)</sub> | High-level dynamic input voltage              |            | 2    |     | V    |
| V <sub>IL(D)</sub> | Low-level dynamic input voltage               |            |      | 0.8 | V    |

NOTE 5: Characteristics are for surface-mount packages only.

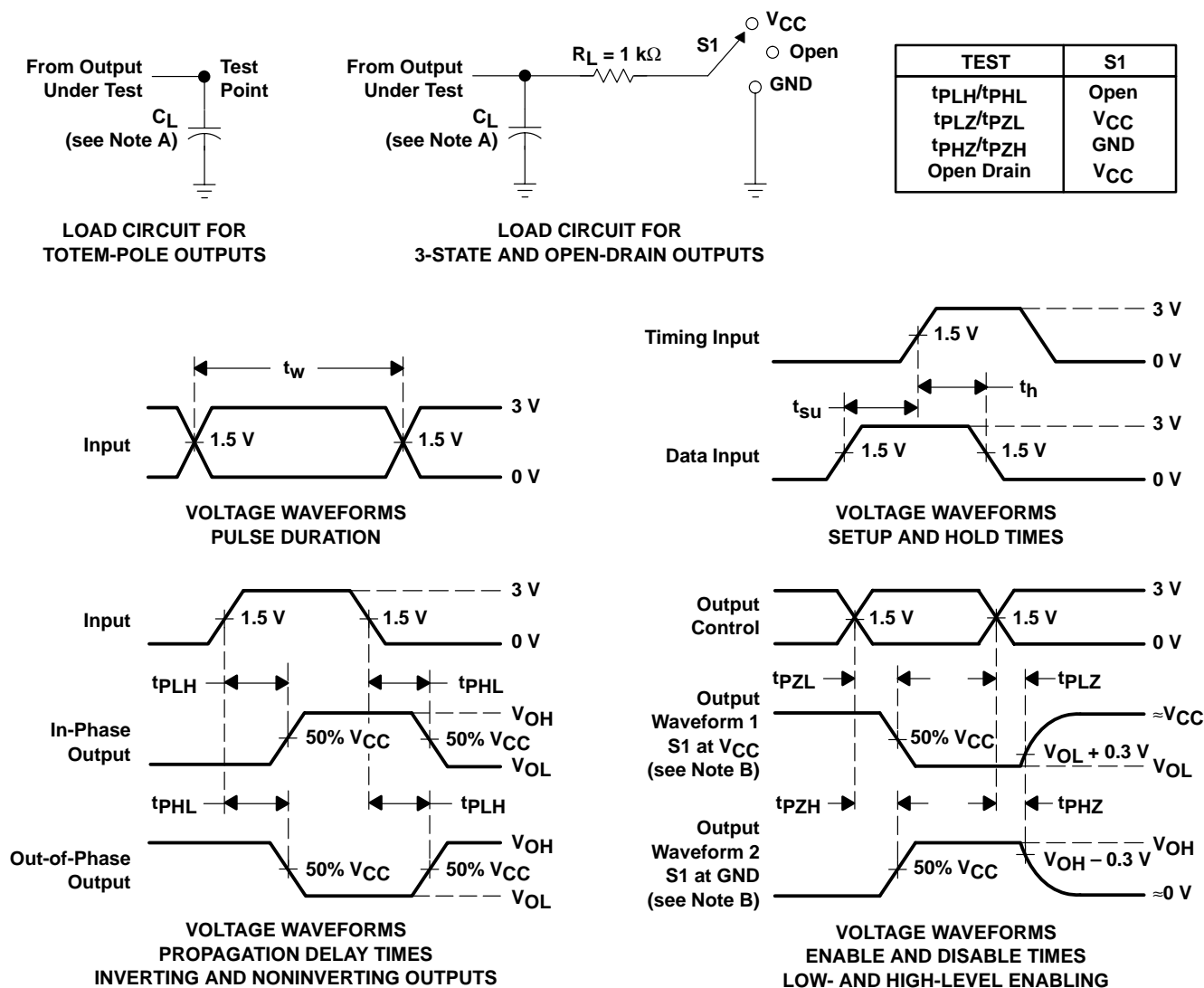
operating characteristics, V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C

| PARAMETER       |                               | TEST CONDITIONS    | TYP | UNIT |
|-----------------|-------------------------------|--------------------|-----|------|
| C <sub>pd</sub> | Power dissipation capacitance | No load, f = 1 MHz | 14  | pF   |

# SN54AHCT04, SN74AHCT04 HEX INVERTERS

SCLS232N – OCTOBER 1995 – REVISED JULY 2003

## PARAMETER MEASUREMENT INFORMATION



- NOTES: A.  $C_L$  includes probe and jig capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 1\text{ MHz}$ ,  $Z_O = 50\ \Omega$ ,  $t_r \leq 3\text{ ns}$ ,  $t_f \leq 3\text{ ns}$ .
- D. The outputs are measured one at a time with one input transition per measurement.
- E. All parameters and waveforms are not applicable to all devices.

**Figure 1. Load Circuit and Voltage Waveforms**

**PACKAGING INFORMATION**

| Orderable Device | Status <sup>(1)</sup> | Package Type | Package Drawing | Pins | Package Qty | Eco Plan <sup>(2)</sup> | Lead/Ball Finish | MSL Peak Temp <sup>(3)</sup> |
|------------------|-----------------------|--------------|-----------------|------|-------------|-------------------------|------------------|------------------------------|
| 5962-9680401Q2A  | ACTIVE                | LCCC         | FK              | 20   | 1           | TBD                     | Call TI          | Level-NC-NC-NC               |
| 5962-9680401QCA  | ACTIVE                | CDIP         | J               | 14   | 1           | TBD                     | Call TI          | Level-NC-NC-NC               |
| 5962-9680401QDA  | ACTIVE                | CFP          | W               | 14   | 1           | TBD                     | Call TI          | Level-NC-NC-NC               |
| SN74AHCT04D      | ACTIVE                | SOIC         | D               | 14   | 50          | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| SN74AHCT04DBLE   | OBSOLETE              | SSOP         | DB              | 14   |             | TBD                     | Call TI          | Call TI                      |
| SN74AHCT04DBR    | ACTIVE                | SSOP         | DB              | 14   | 2000        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| SN74AHCT04DBRE4  | ACTIVE                | SSOP         | DB              | 14   | 2000        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| SN74AHCT04DG4    | ACTIVE                | SOIC         | D               | 14   | 50          | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| SN74AHCT04DGV    | ACTIVE                | TVSOP        | DGV             | 14   | 2000        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| SN74AHCT04DGVRE4 | ACTIVE                | TVSOP        | DGV             | 14   | 2000        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| SN74AHCT04DR     | ACTIVE                | SOIC         | D               | 14   | 2500        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| SN74AHCT04DRG4   | ACTIVE                | SOIC         | D               | 14   | 2500        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| SN74AHCT04N      | ACTIVE                | PDIP         | N               | 14   | 25          | Pb-Free (RoHS)          | CU NIPDAU        | Level-NC-NC-NC               |
| SN74AHCT04NE4    | ACTIVE                | PDIP         | N               | 14   | 25          | Pb-Free (RoHS)          | CU NIPDAU        | Level-NC-NC-NC               |
| SN74AHCT04NSR    | ACTIVE                | SO           | NS              | 14   | 2000        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| SN74AHCT04NSRE4  | ACTIVE                | SO           | NS              | 14   | 2000        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| SN74AHCT04PW     | ACTIVE                | TSSOP        | PW              | 14   | 90          | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| SN74AHCT04PWE4   | ACTIVE                | TSSOP        | PW              | 14   | 90          | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| SN74AHCT04PWG4   | ACTIVE                | TSSOP        | PW              | 14   | 90          | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| SN74AHCT04PWLE   | OBSOLETE              | TSSOP        | PW              | 14   |             | TBD                     | Call TI          | Call TI                      |
| SN74AHCT04PWR    | ACTIVE                | TSSOP        | PW              | 14   | 2000        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| SN74AHCT04PWRE4  | ACTIVE                | TSSOP        | PW              | 14   | 2000        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| SN74AHCT04PWRG4  | ACTIVE                | TSSOP        | PW              | 14   | 2000        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-1-260C-UNLIM           |
| SN74AHCT04RGYR   | ACTIVE                | QFN          | RGY             | 14   | 1000        | Green (RoHS & no Sb/Br) | CU NIPDAU        | Level-2-260C-1YEAR           |
| SNJ54AHCT04FK    | ACTIVE                | LCCC         | FK              | 20   | 1           | TBD                     | Call TI          | Level-NC-NC-NC               |
| SNJ54AHCT04J     | ACTIVE                | CDIP         | J               | 14   | 1           | TBD                     | Call TI          | Level-NC-NC-NC               |
| SNJ54AHCT04W     | ACTIVE                | CFP          | W               | 14   | 1           | TBD                     | Call TI          | Level-NC-NC-NC               |

<sup>(1)</sup> The marketing status values are defined as follows:

---

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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J (R-GDIP-T\*\*)

14 LEADS SHOWN

# CERAMIC DUAL IN-LINE PACKAGE



| PINS **<br>DIM | 14                     | 16                     | 18                     | 20                     |
|----------------|------------------------|------------------------|------------------------|------------------------|
| A              | 0.300<br>(7,62)<br>BSC | 0.300<br>(7,62)<br>BSC | 0.300<br>(7,62)<br>BSC | 0.300<br>(7,62)<br>BSC |
| B MAX          | 0.785<br>(19,94)       | .840<br>(21,34)        | 0.960<br>(24,38)       | 1.060<br>(26,92)       |
| B MIN          | —                      | —                      | —                      | —                      |
| C MAX          | 0.300<br>(7,62)        | 0.300<br>(7,62)        | 0.310<br>(7,87)        | 0.300<br>(7,62)        |
| C MIN          | 0.245<br>(6,22)        | 0.245<br>(6,22)        | 0.220<br>(5,59)        | 0.245<br>(6,22)        |



4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package is hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package can be hermetically sealed with a ceramic lid using glass frit.
  - Index point is provided on cap for terminal identification only.
  - Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB



## FK (S-CQCC-N\*\*)

## LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a metal lid.
  - D. The terminals are gold plated.
  - E. Falls within JEDEC MS-004

## N (R-PDIP-T\*\*)

16 PINS SHOWN

## PLASTIC DUAL-IN-LINE PACKAGE



| PINS **             | 14               | 16               | 18               | 20               |
|---------------------|------------------|------------------|------------------|------------------|
| DIM                 |                  |                  |                  |                  |
| A MAX               | 0.775<br>(19,69) | 0.775<br>(19,69) | 0.920<br>(23,37) | 1.060<br>(26,92) |
| A MIN               | 0.745<br>(18,92) | 0.745<br>(18,92) | 0.850<br>(21,59) | 0.940<br>(23,88) |
| MS-001<br>VARIATION | AA               | BB               | AC               | AD               |



14/18 Pin Only  
20 Pin vendor option

4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - The 20 pin end lead shoulder width is a vendor option, either half or full width.

## DGV (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE

24 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.  
 D. Falls within JEDEC: 24/48 Pins – MO-153  
 14/16/20/56 Pins – MO-194

## D (R-PDSO-G14)

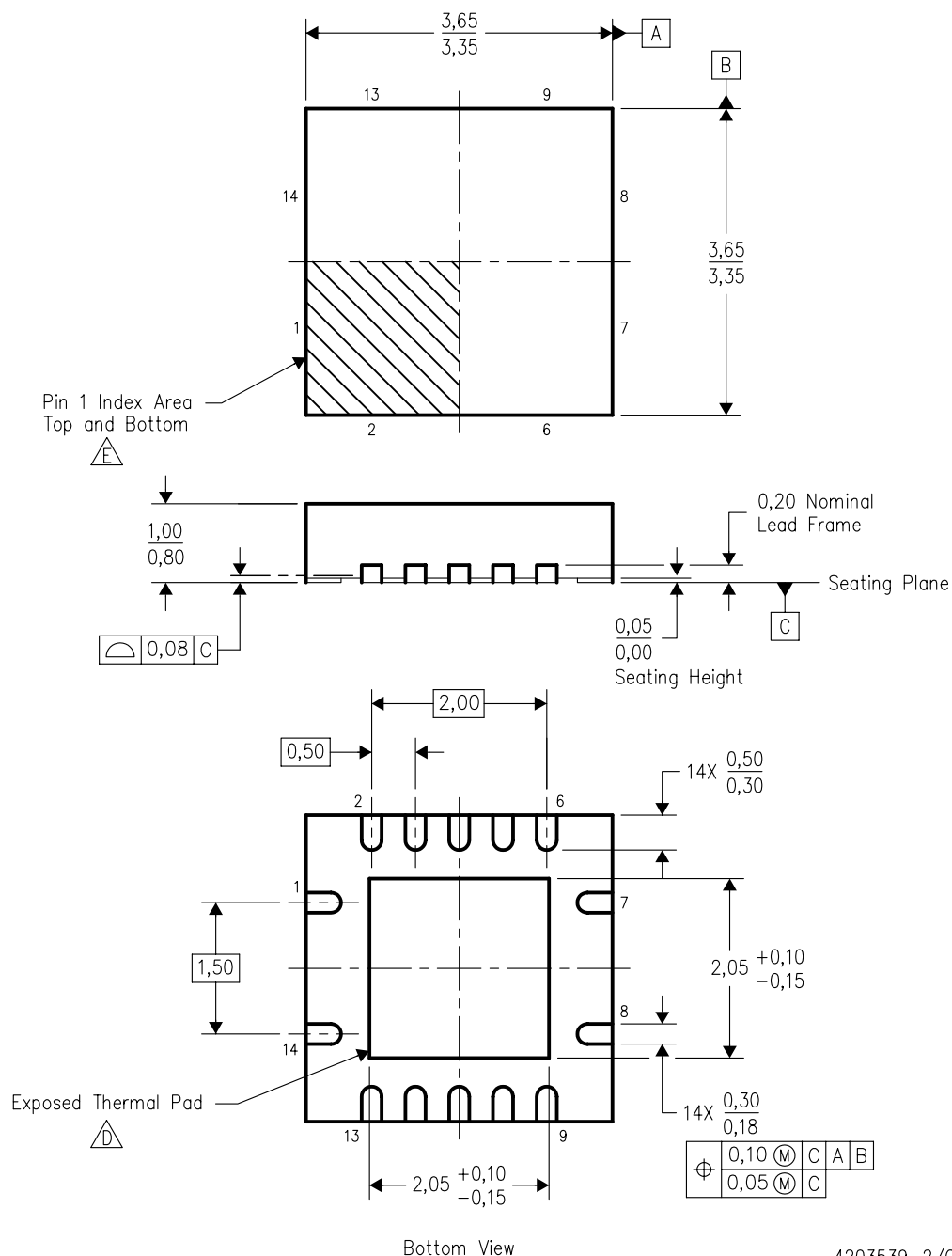
## PLASTIC SMALL-OUTLINE PACKAGE



4040047-3/F 07/2004

RGY (S-PQFP-N14)

PLASTIC QUAD FLATPACK



4203539-2/G 04/2005

- NOTES:
- All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - This drawing is subject to change without notice.
  - QFN (Quad Flatpack No-Lead) package configuration.
  - The package thermal pad must be soldered to the board for thermal and mechanical performance.
  - Pin 1 identifiers are located on both top and bottom of the package and within the zone indicated. The Pin 1 identifiers are either a molded, marked, or metal feature.
  - Package complies to JEDEC MO-241 variation BA.

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



| DIM \ PINS ** | 14    | 16    | 20    | 24    |
|---------------|-------|-------|-------|-------|
| A MAX         | 10,50 | 10,50 | 12,90 | 15,30 |
| A MIN         | 9,90  | 9,90  | 12,30 | 14,70 |

4040062/C 03/03

- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

## DB (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-150

## PW (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-153



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